ABSTRACT

There is provided a technique that includes: (a) forming an inhibitor layer on a first surface of a substrate, which includes the first surface and a second surface, by supplying a modifying agent that reacts with the first surface to the substrate; (b) forming a first film on the second surface by supplying a first film-forming agent, at least a portion of which being provided with a first energy, to the substrate in which the inhibitor layer is formed on the first surface; and (c) forming a second film on the first film formed on the second surface by supplying a second film-forming agent, at least a portion of which being provided with a second energy which is higher than the first energy, to the substrate in which the first film is formed on the second surface.

FIG. 4